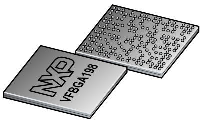
SOT2155-1

VFBGA198, very thin fine-pitch ball grid array package, 198 terminals, 0.5 mm pitch, 9.0 mm x 9.35 mm x 0.834 mm body

30 July 2024

Package information



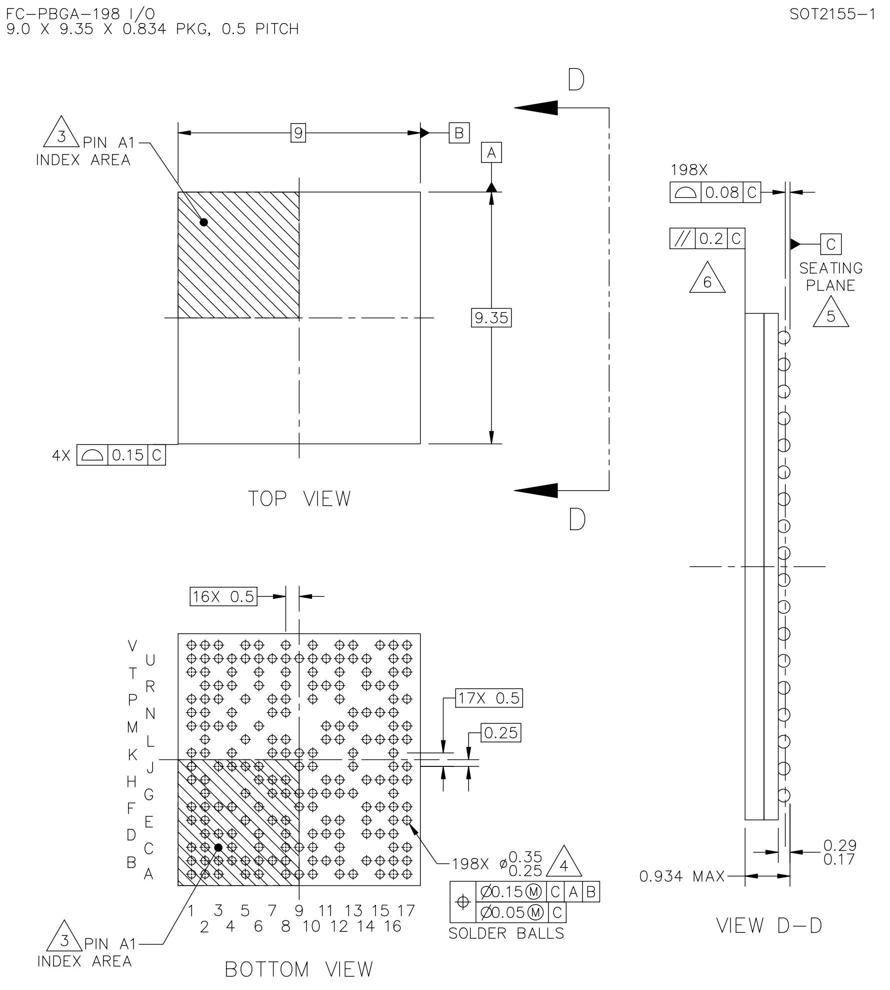
1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA198
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	01-06-2022
Manufacturer package code	98ASA01805D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	9	-	mm
package width	-	9.35	-	mm
seated height	-	0.834	0.934	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	198	-	

2 Package outline



DATE: 28 JUN 2024

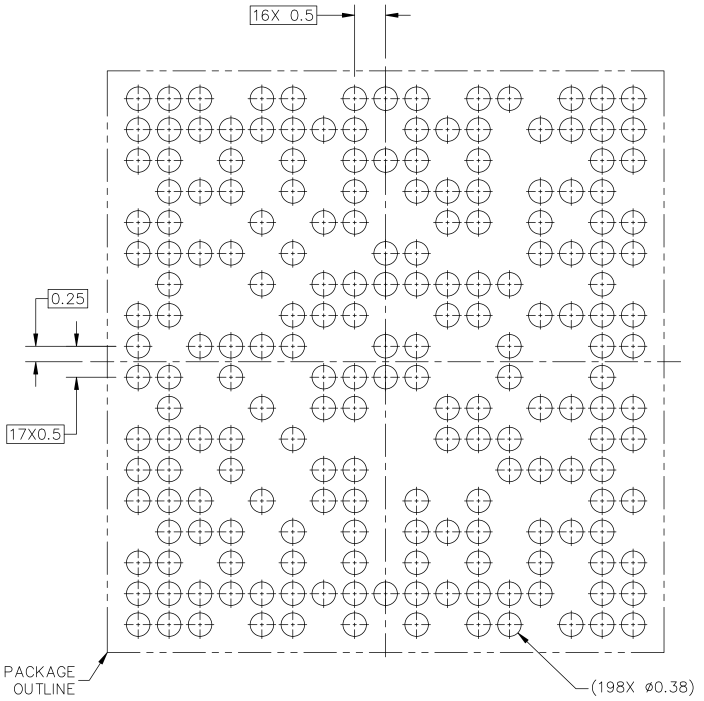
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01805D	REVISION: A	

Figure 1. Package outline VFBGA198(SOT2155-1)

3 Soldering

FC-PBGA-198 I/O
9.0 X 9.35 X 0.834 PKG, 0.5 PITCH

SOT2155-1



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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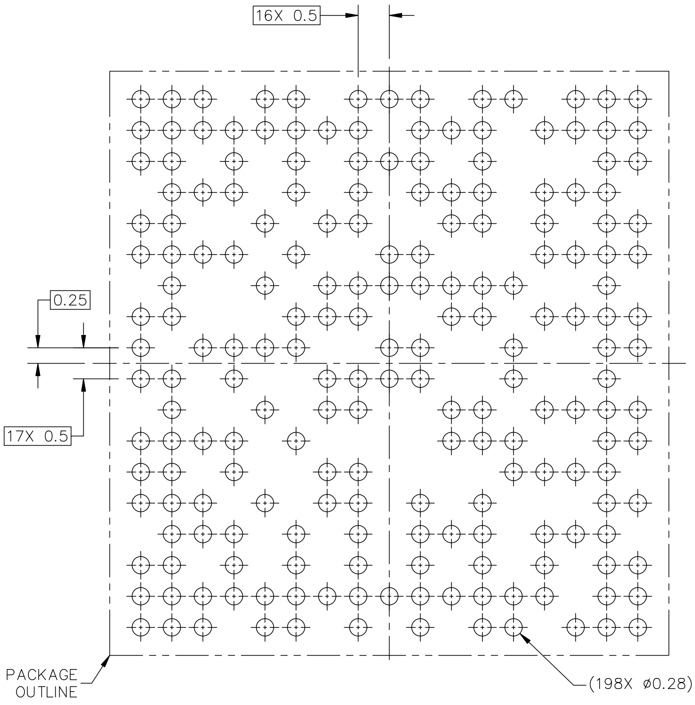
Figure 2. Reflow soldering footprint part1 for VFBGA198(SOT2155-1)

FC–PBGA–198 I/O
9.0 X 9.35 X 0.834 PKG, 0.5 PITCH

SOT2155–1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

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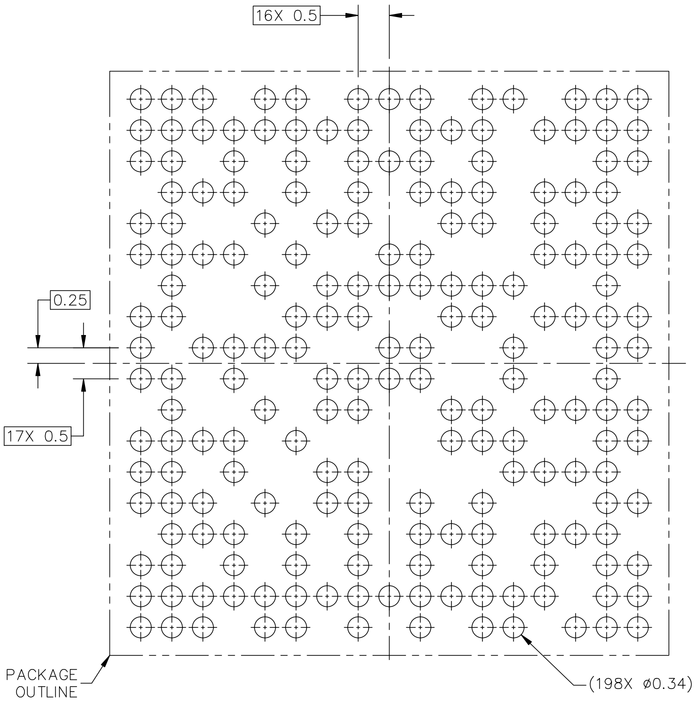
DATE: 28 JUN 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01805D	REVISION: A	

Figure 3. Reflow soldering footprint part2 for VFBGA198(SOT2155-1)

FC-PBGA-198 I/O
9.0 X 9.35 X 0.834 PKG, 0.5 PITCH

SOT2155-1



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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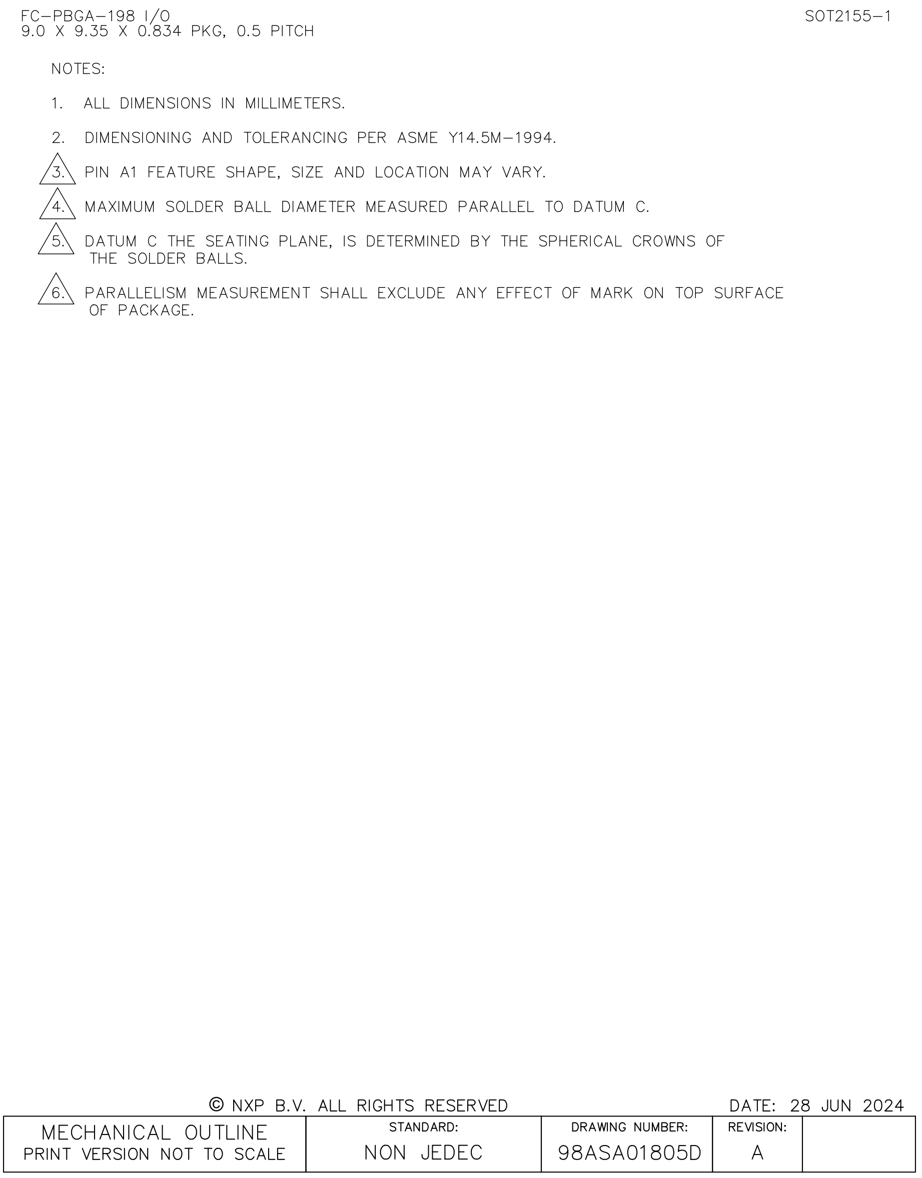
DATE: 28 JUN 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01805D	REVISION: A	

Figure 4. Reflow soldering footprint part3 for VFBGA198(SOT2155-1)



FC–PBGA–198 I/O
9.0 X 9.35 X 0.834 PKG, 0.5 PITCH

SOT2155–1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. △ PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. △ MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. △ DATUM C THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. △ PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

DATE: 28 JUN 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD:	DRAWING NUMBER:	REVISION:	
	NON JEDEC	98ASA01805D	A	

Figure 5. Package outline note VFBGA198(SOT2155-1)

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